

**ABSTRACT OF THE DISCLOSURE**

A process for cleaning the surface of a semiconductor wafer. The process has the following steps: a) conveying a component selected from the group  
5 consisting of a dense gas component, a liquid component and a mixture thereof to a bellows accumulator having a bellows therein; b) applying an elevated pressure to said bellows sufficient to discharge the component from the bellows onto said surface of the wafer; and c) contacting the component with the surface of the wafer. There is also a system for cleaning the surface of a semiconductor wafer  
10 and for mixing a dense gas component and a liquid component.